



CyberOptics Features Advanced Airborne Particle Sensor Technology at SEMICON Europa 2014

CyberOptics spokesperson shares best practice process insights for reticle environments

Grenoble, France —October 7, 2014— [CyberOptics® Corporation](#) (NASDAQ: CYBE), a world leader in intelligent inspection and sensing solutions for electronics assembly and semiconductor process equipment, will showcase its most efficient and effective wireless measurement devices for chamber gapping, leveling, wafer handoff teaching, vibration and airborne particle measurement, at the upcoming [SEMICON Europa](#), Oct. 7-9, 2014 in Booth #930 at the Alpexpo.

Featured in the booth will be the company's most advanced airborne particle sensing solutions, which provide a 60% increase in sensitivity, resulting in improved fab yields and equipment uptime.

In addition, on Thursday, October 9, at 13:30 a [presentation](#) from Allyn Jackson, Field Application Engineer for CyberOptics, will detail how best to increase efficiency and effectiveness of processes related to airborne particle measurement in reticle mask environments.

“Stringent manufacturing requirements and the need to maximize both yields and tool uptimes requires best-in-class practices for a contamination-free process environment,” said Allyn Jackson, Field Application Engineer. “Quickly identifying when and where airborne particles originate and the source of the contamination is challenging with traditional surface scan wafer methods. Whether for equipment diagnostics, particle qualification or preventative maintenance, equipment engineers need to identify and troubleshoot airborne particle issues efficiently and effectively.”

Engineers can rely on CyberOptics' ReticleSense™ measurement devices, which are an extension of the proven WaferSense® wafer-shaped Airborne Particle Sensor (APS) devices in use at semiconductor fabs worldwide including the three largest manufacturers where a contamination-free environment is critical. The ReticleSense Airborne Particle Sensor (ASPR) can quickly check the dozens of particle sensitive chambers that otherwise might take long hours or even days to check with multiple surface scan wafers.

Along with the ReticleSense APSR, CyberOptics will also showcase the entire WaferSense product line. This includes its WaferSense wafer-shaped form factor products adopted by the semiconductor industry since 2004 that provide leveling, gap measurement, robot teaching, vibration measurement and airborne particle detection solutions. The WaferSense measurement portfolio including the Auto Leveling System (ALS), the Auto Gapping System (AGS), the Auto Vibration System (AVS), the Auto Teaching System (ATS) and the Airborne Particle Sensor (APS) are available now in 200mm, 300mm and 450mm wafer sizes. Additionally, both APS and ALS are available in 150mm sizes. The ReticleSense Airborne Particle Sensor (APSR) and ReticleSense Auto Leveling System (ALSR) products are available in a reticle shaped form factor.

For more information about the entire line of CyberOptics solutions please visit the company's website at www.cyberoptics.com.

About CyberOptics

Founded in 1984, CyberOptics Corporation is a leading provider of sensors and inspection systems that provide process yield and through-put improvement solutions for the global electronic assembly and semiconductor capital equipment markets. Our products are deployed on production lines that manufacture surface mount technology circuit boards and semiconductor process equipment. Through internal development and acquisitions, CyberOptics is strategically repositioning itself to become a global leader in high-precision 3D sensors. Headquartered in Minneapolis, Minnesota, CyberOptics conducts worldwide operations through facilities in North America, Asia and Europe.

Statements regarding the Company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: market conditions in the global SMT and semiconductor capital equipment industries; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required for meeting customer orders; unanticipated product development challenges; the effect of world events on our sales, the majority of which are from foreign customers; product introductions and pricing by our competitors; the level of revenue and loss we record in 2014; the success of our 3D technology initiatives; expectations regarding LDI and its impact on our operations; integration risks associated with LDI and other factors set forth in the Company's filings with the Securities and Exchange Commission.

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